

承認書

APPROVAL SHEET

客戶名稱

Customer

: **Wistron Corporation**

客戶料號

Customer P/N

: **25.90143.001**

適用機種

Model No.

: **GANNET**

送件日期

Submitted Date

: **September. 05,**

承認日期

Approved Date

瀚宇料號

HannStar P/N

: **WA00101**

品名

Description

: **BLUETOOTH for GANNET system**

APPROVED	承認編號
	承認人簽章



瀚宇電子股份有限公司

HannStar Electronics Corp.

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瀚宇電子股份有限公司
HannStar Electronics Corp.

承認書索引

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Customer P/N: 25.90143.001

Model: GANNET

HSE P/N: WA00101

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HannStar Electronics Corp.

1. Introduction

Antennas for Bluetooth system

Bluetooth Antenna (PCB type)

1. Application: Left side in motherboard location
2. Cable length: 150mm, White
(IPEX connector with 1.13mm RF cable)



2. Revision History

Date	Version	Change Description
09/05/2003	A	New Release

3. Product Spec.

3.1 Antenna Design Specification

Measure environment LCD angle 110 degree

3.1.1 VSWR

VSWR	2G4 ISM (2.40GHz-2.483GHz)		
	2.40GHz	2.45GHz	2.50GHz
Bluetooth antenna	2		

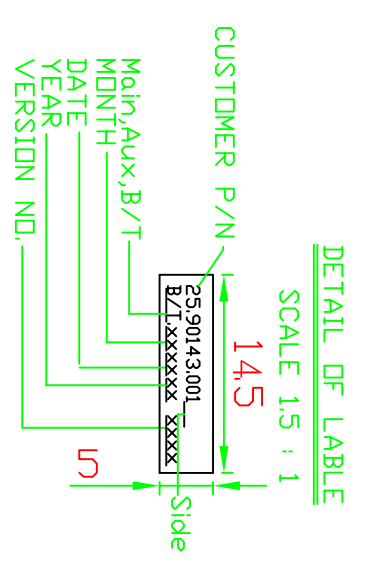
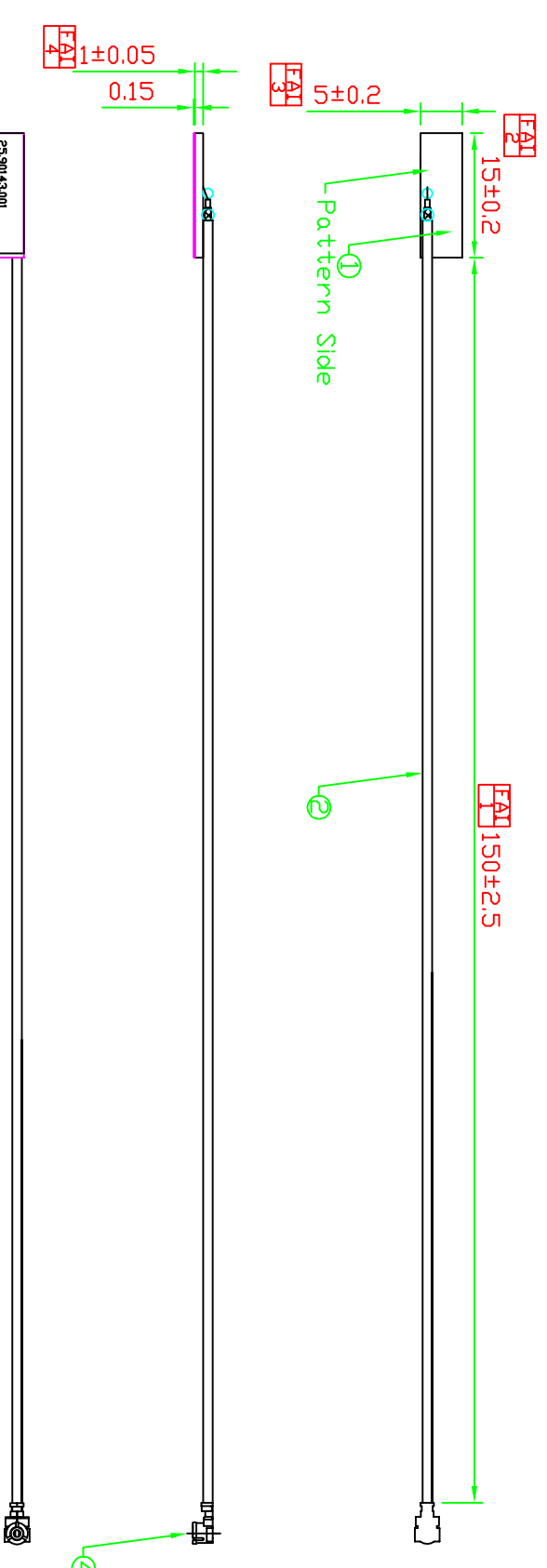
3.1.2 Average gain

Average Gain	2G4 ISM (2.40GHz-2.483GHz)		
	2.40GHz	2.45GHz	2.50GHz
Bluetooth Antenna	-5		

3.2 Mechanical Spec.

See the attached drawing

REVISIONS			DATE
REV.	ECN NO.	ECN BY.	DESCRIPTION
A	EP030309	Leo	New Release
			09/05/03



ITEM NO.	QTY	RECD	PART NUMBER	DESCRIPTION
1	1		U010-007-0059	PCB Antenna 5x15 t=1.0
2	1		U011-002-0013-3	Coaxial Cable $\phi 1.13$ White
3	1		U013-011-0026	TAPE Sony T4000 t=0.15
4	1		U006-002-0010	I-PEX Connector

X ± 0.3 XX ± 0.2		HannStar Electronics Corp.	
UNIT: mm (Inch)	SCALE: NONE	APPD: James 08/25/03	Title: WA00101 成品圖
SCALE: NONE	DR: Leo 08/25/03	CHKD: Allen 08/25/03	DWG NO.: WA00101
SHEET: 1 of 1		REV: A	

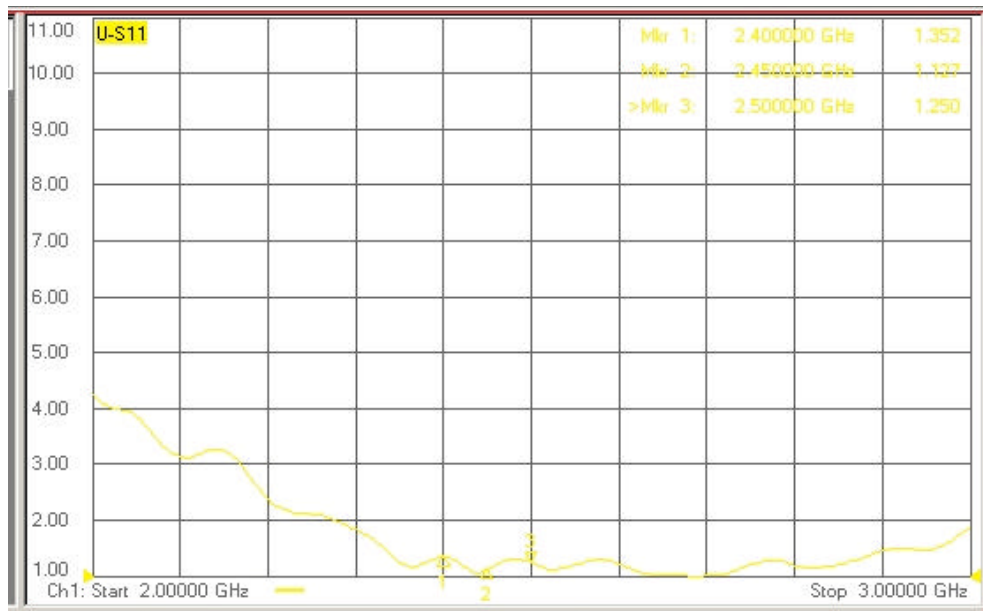
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3.3 Antenna BOM structure

NO.	Part NO.	Description	Q ' ty
1	U011-002-0013-2	Hitachi Cable O1.13 White 150mm	1
2	U010-007-0059	PCB 5x15mm	1
3	U006-002-0010	I-PEX Connector	1
4	U013-011-0026	Type SONY T4000	1

3.4 Antenna Test Results

3.4.1 VSWR

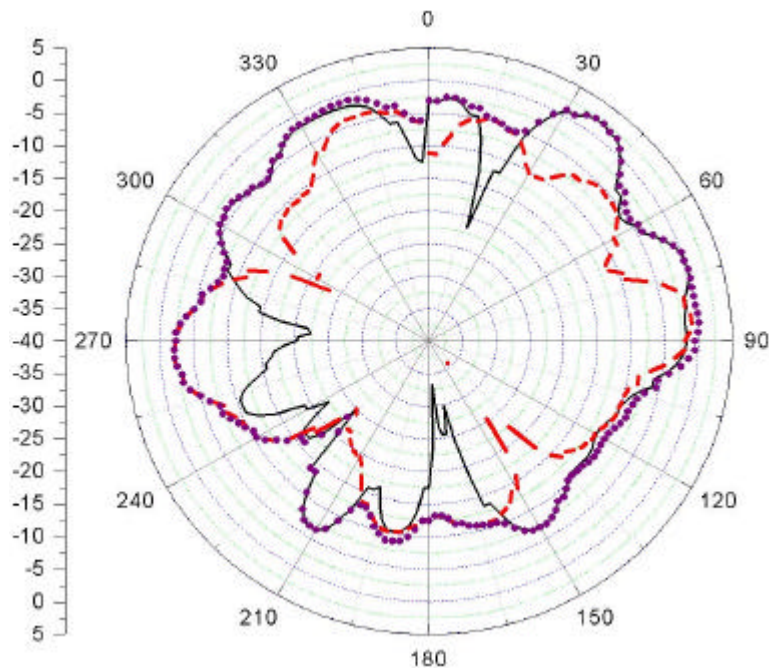


VSWR	2G4 ISM (2.40GHz-2.483GHz)		
	2.40GHz	2.45GHz	2.50GHz
Bluetooth Antenna	1.1218	1.1227	1.1244

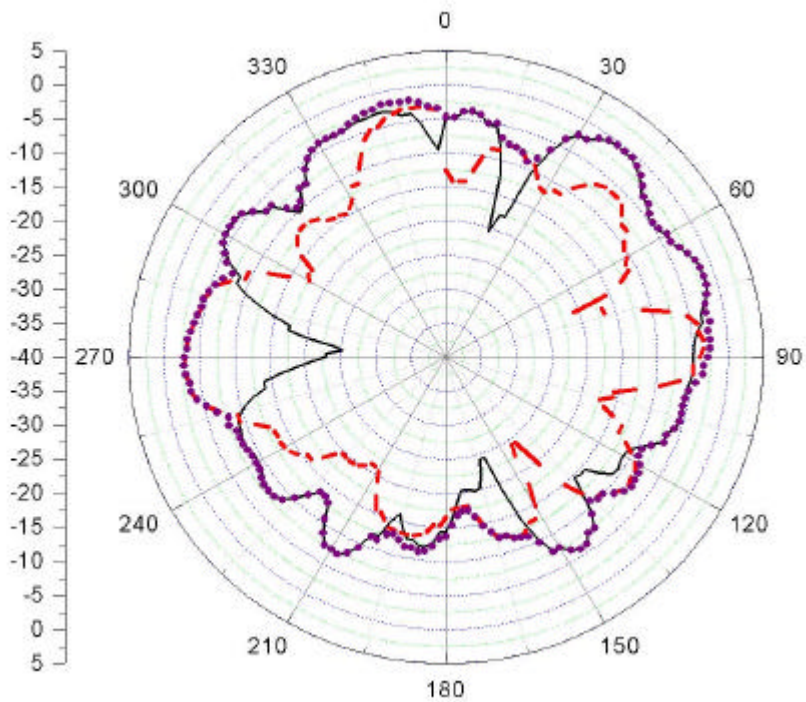
3.4.2 Radiation Pattern

Gain(dBi)		2G4 ISM (2.40GHz-2.483GHz)		
		2.40GHz	2.45GHz	2.50GHz
Bluetooth Antenna	Peak	1.23	-0.49	0.15
	Average	-4.08	-4.19	-4.47

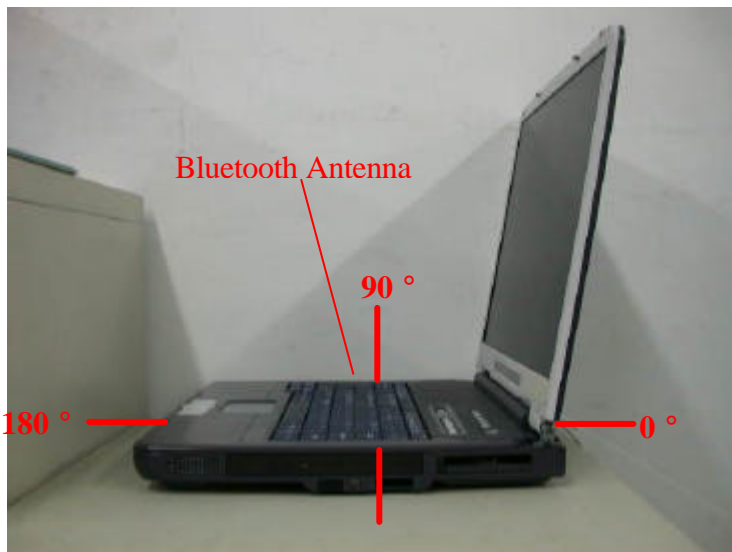
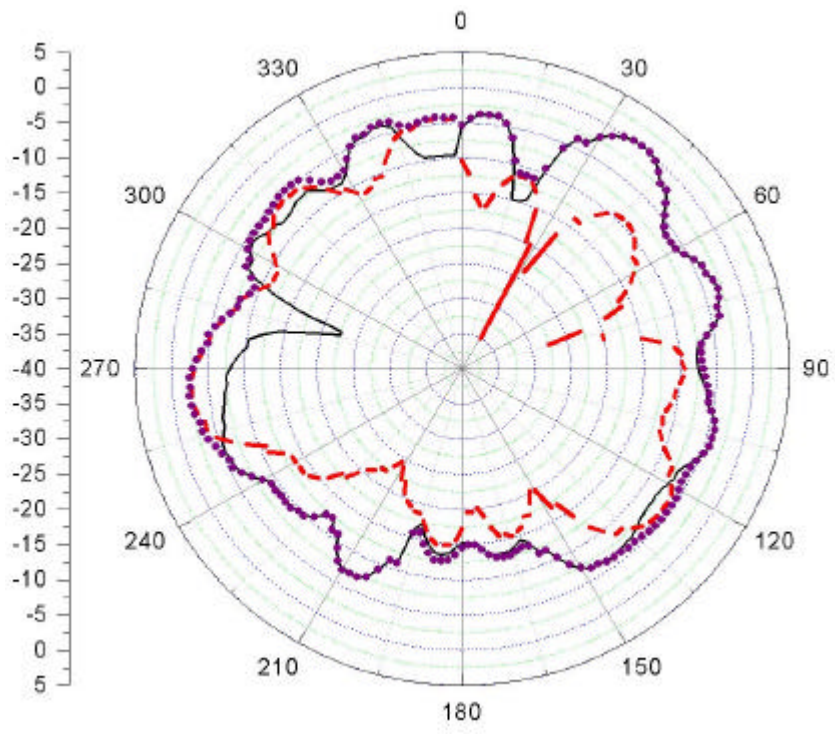
Bluetooth Antenna @ - 2.40 GHz



Bluetooth Antenna @ - 2.45 GHz



Bluetooth Antenna @ - 2.483 GHz



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270 °

4. Environment Performance Test

4.1 Introduction

This EQT (Environment Qualification Test) report is used to describe the final status of PCB type Antenna about the EQT test results.

4.2 Test Items and Results

4.2.1 the following table is used to show the final status of PCB type Antenna.

Test Item	Specification	Test Result	Tested By	Remark
Thermal Shock	Temperature range:-20 ~80 Hold Time:30 min Total cycle:20 cycles	Pass	HSE	
Vibration (Need NB)	Frequency 5 to 500Hz Overall rms level : 0.6G P-P~2.0G P-P Duration of test : 1 Hr/cycle Number of axes : X,Y,Z 1 cycle/axis	Pass	HSE	
Salt Spray	Chamber temperature : 35 Salt : 5% Hold time : 48 Hr	Pass	HSE	
Contact Engagement & Separation Forces	Speed : 22 mm/mint Inspection Item : Soldering Pull strength Soldering pull strength > 1 kgw	Pass	HSE	

VSWR	2G4 ISM (2.40GHz-2.483GHz)			
	S/N	2.40GHz	2.45GHz	2.50GHz
Before Thermal Shock Test	01	1.1218	1.1227	1.1244
	02	1.1352	1.1312	1.1364
	03	1.3122	1.1532	1.2123
After Thermal Shock Test	01	1.5623	1.4313	1.6325
	02	1.5325	1.3256	1.5421
	03	1.4562	1.4121	1.5213

VSWR	Bluetooth Antenna			
	2G4 ISM (2.40GHz-2.483GHz)			
	S/N	2.40GHz	2.45GHz	2.50GHz
Before Vibration Test	01	1.21	1.23	1.22
	02	1.25	1.26	1.28
	03	1.13	1.11	1.16
After Vibration Test	01	1.46	1.35	1.50
	02	1.48	1.45	1.55
	03	1.54	1.50	1.61

VSWR	Bluetooth Antenna (Right)			
	2G4 ISM (2.40GHz-2.483GHz)			
	S/N	2.40GHz	2.45GHz	2.50GHz
Before Salt Spray Test	01	1.25	1.23	1.26
	02	1.16	1.12	1.13
	03	1.19	1.17	1.18
After Salt Spray Test	01	1.50	1.44	1.48
	02	1.45	1.46	1.42
	03	1.50	1.49	1.53

Main Antenna (Right)						
Number	1	2	3	Max	Min	Avg
Soldering Pull strength (Unit:kg)	3.985	3.957	3.967	3.985	3.957	3.696

5. Package

See the attached drawing.

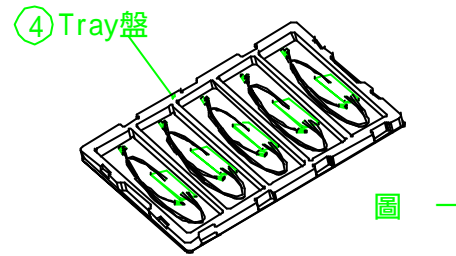
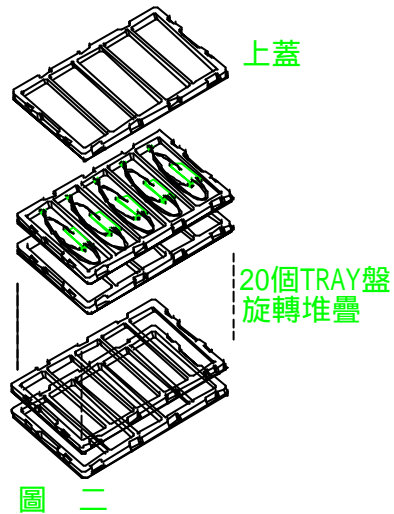
HannStar	類別	包裝作業標準	適用客戶	國內一般客戶	適用產品	Wireless Lan	包裝類別	Tray 盤
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編號: P899-T007
制定日期: 90.07.10
修訂日期:
版次: 00
頁次: 01

包裝作業說明:

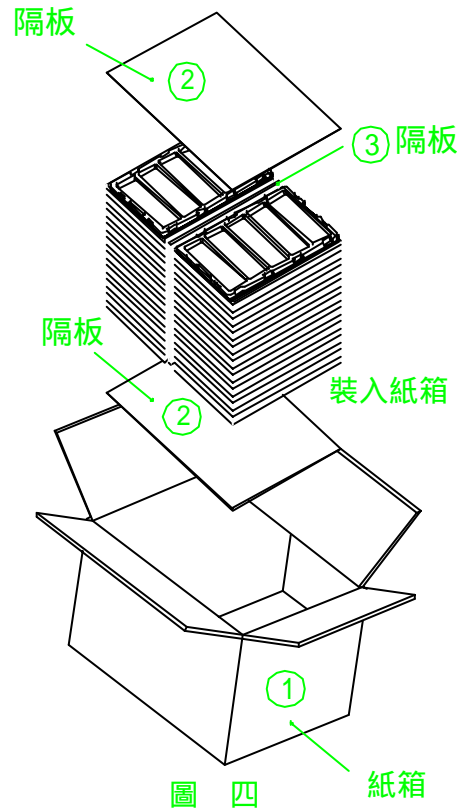
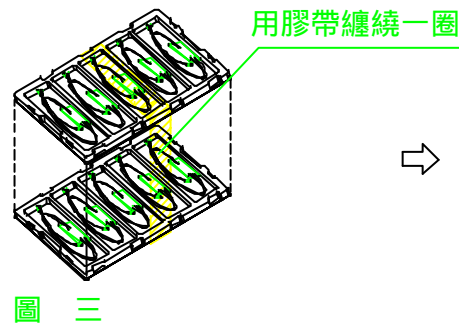
一. 成品包裝方式:

每個TRAY盤共裝15PCS
 成品, 每小格放3PCS,
 方向如圖(一)所示.
 每疊20個TRAY盤, 最上
 層用一個空TRAY做上蓋
 每疊成品300PCS, 如圖
 (二)所示.
 再用膠帶將TRAY 盤小邊
 纏繞一圈, 以防 脫落, 如
 圖(三)所示.



二. 紙箱包裝方式:

裝箱前, 先放一片隔板在
 箱底, 放入成品二疊 中間
 須以隔板分開, 如圖示(四)
 所示, 完成後封箱前再放一
 片隔板. 蓋上箱子用膠帶封
 合, 在側 面貼上標籤紙一張
 如有零 箱部分, 出貨 時須以
 緩衝物填滿.



備註:

注意事項:

1. 包裝前請確認成品無夾帶綿絮或污染物.
2. 包裝時不得有毀損以及污染成品之情形發生.
3. 包裝時必須注意成品與包材之方向性, 不得有方向錯誤之情形發生.
4. TRAY是否有變形破裂情況發生.
5. TRAY和TRAY結合是否有過緊或鬆脫情況發生.

核定:
覆核:
制定: 蔡麗文

7. VSWR CPK

Cpk of Antenna

Part Number: 25.90019.001

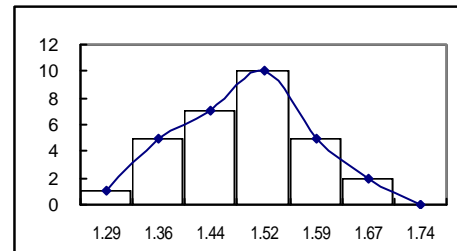
				Measurement Value																								
Item	Spec.	Tolerance +	Tolerance -	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	21	22	23	24	25
VSWR (b)	2.00	0	0	1.32	1.42	1.36	1.52	1.42	1.48	1.36	1.54	1.63	1.57	1.36	1.29	1.38	1.54	1.27	1.43	1.55	1.38	1.37	1.25	1.31	1.45	1.46	1.43	1.45
				26	27	28	29	30	31	32	33	34	35															
				1.49	1.39	1.33	1.48	1.47																				
組界			5	1.25	1.33	1.40	1.48	1.55	1.63	1.71																		
				26	27	28	29	30	31	32	33	34	35															
組界																												
				26	27	28	29	30	31	32	33	34	35															
組界																												
組界																												

Engineering Specification			
工程尺寸	VSWR (b)		
工程規格	Product spec	1.5000	1.7500
正公差	Tolerance	0.5000	0.7500
負公差	Tolerance	0.5000	0.7500
工程上限	USL	2	2.5
工程下限	LSL	1	1
Actual Data			
量測尺寸	VSWR (b)		
平均數	X bar	1.4233	
標準差	Sigma	0.0940	
中間值	Median	1.4250	
眾數	Mode	1.3600	
最大值	Max	1.6300	
最小值	Min	1.2500	
UCL 3個標準差	1 Sigma	1.5173	
	2 Sigma	1.6113	
	3 Sigma	1.7052	
LCL 3個標準差	1 Sigma	1.3294	
	2 Sigma	1.2354	
	3 Sigma	1.1414	
製程能力	雙邊CP	1.77	
	單邊CPL	1.50	
	單邊CPU	2.05	
	單邊CP	1.50	
	Ca	0.00	
	Cpk	1.77	

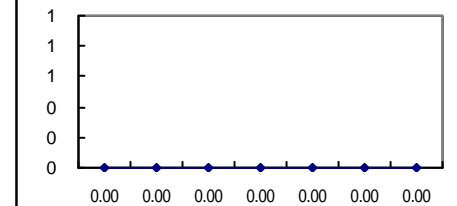
VSWR		B		C	
組別	次數	組別	次數	組別	次數
1.29	1	#####	0	#####	0
1.36	5	#####	0	#####	0
1.44	7	#####	0	#####	0
1.52	10	#####	0	#####	0
1.59	5	#####	0	#####	0
1.67	2	#####	0	#####	0
1.74	0	#####	0	#####	0

Remark:
Gauge:

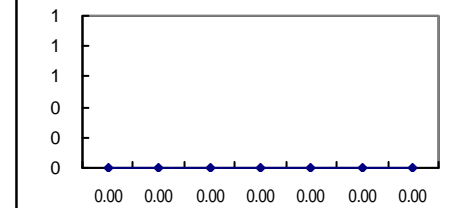
VSWR (b)



VSWR (a)



Dimension C



- **Cable – Hitachi**

SPECIFICATION

FOR

UL RECOGNIZED FEP INSULATED HIGH FREQUENCY COAXIAL CABLE

[P/N ;UL1745]

Quantity

Your Ref. No.

Our Ref. No.

Signed by *F. Shimizu*

Fumio Shimizu

Manager

Electronic Wire & Cable design department
Hitaka works, Electronic Supplies Group

Hitachi Cable, Ltd.

Issue and revision record

Rev. No.	Issue date	Item	Prepared by	Reviewed by	Approved by
—	Nov. 8, 2001	Initial issue	H. Tanaka	H.Ito	F. Shimizu
1	Nov. 16, 2001	<p>Revised Point [UL1745-SB CX-50 1×32AWG(7/0.08)D=1.13]</p> <ul style="list-style-type: none"> • Change Diameter of Insulation 0.66 → 0.68 • Outer conductor material is Changed tinned annealed copper wire ↓ Silver plated annealed copper wire • Construction of Outer conductor 5×16 → 4×16 • Change Diameter of Jacket 1.13±0.1 → 1.13^{+0.08}_{-0.05} • Nominal attenuation is changed [UL1745-SB CX-50 1×32AWG(7/0.08)D=1.32] • Change Diameter of Insulation 0.66 → 0.68 • Construction of Outer conductor 5×16 → 4×16 • Nominal attenuation is changed 	<p><i>N. Ono</i> N. Ono</p>	<p><i>H. Ito</i> H.Ito</p>	<p><i>F. Shimizu</i> F. Shimizu</p>

1. Scope

This specification covers UL recognized Fluoroethylene-propylene insulated high frequency coaxial cable.

[UL1745 : 90°C、30V]

Use : Internal wiring of Class 2 Circuits of Electronic Equipment.

2. Construction and Properties

HCL P/N	HCLI-TPE P/N	Construction and Properties
UL1745-SB CX-50 1×30AWG(1/0.26)D=1.25	RFX50-SS30-125	Table 1
UL1745-SB CX-50 1×30AWG(7/0.102)D=1.48	RFX50-SS30-148	
UL1745-SB CX-50 1×32AWG(7/0.08)D=1.13	RFX50-SS32-113	Table 2
UL1745-SB CX-50 1×32AWG(7/0.08)D=1.32	RFX50-SS32-132	
UL1745-DSB CX-50 1×32AWG(7/0.08)D=1.32	RFX50-DS32-132	Table 3
UL1745-SB CX-50 1×34AWG(7/0.064)D=0.98	RFX50-SS34-098	
UL1745-SB CX-50 1×36AWG(7/0.05)D=0.81	RFX50-SS36-081	

3. Marking

3.1 Marking on the wire

No marking on the wires.

3.2 Marking on the tag attached to reel

Each reel shall be tagged to show the following information with UL stamp.

- | | |
|----------------------|---------------------------|
| (1) UL Style | (8) File No. |
| (2) Conductor size | (9) Rating temperature |
| (3) No. of conductor | (10) Rating voltage |
| (4) Color | (11) Date of manufacture |
| (5) Lot No. | (12) Insulation thickness |
| (6) Length | (13) Name of manufacture |
| (7) Use | |

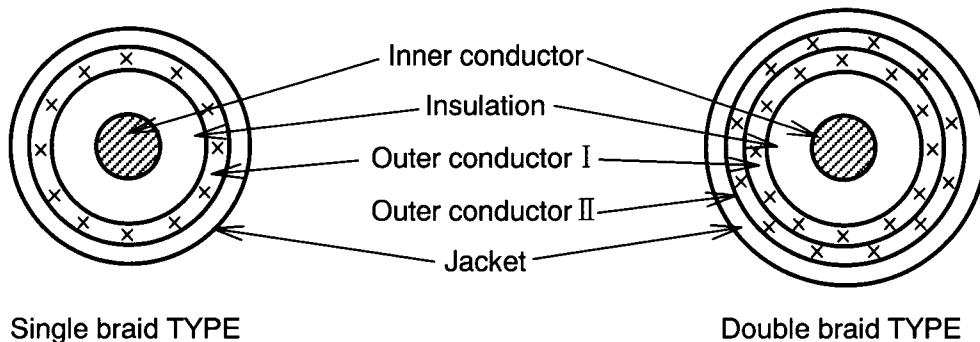


Fig.1 Cross-section of cable

Table 1 Construction and Properties (30AWG)

Item	Unit	Specified Value		
HCL P/N	—	UL1745-SB CX-50 1×30AWG(1/0.26)D=1.25	UL1745-SB CX-50 1×30AWG(7/0.102)D=1.48	
HCLI-TPE P/N	—	RFX50-SS30-125	RFX50-SS30-148	
Inner Conductor	Material	—	silver plated copper clad steel wire	
	AWG size	—	30	
	Stranding	No./mm	1/0.26	7/0.102
	Diameter	mm	0.26±0.008	0.30±0.03
	Number	—	1	
Insulation	Material	—	Fluoroethylene-propylene(FEP)	
	Thickness	mm	Nom. 0.27	Nom. 0.27
	Diameter	mm	0.80±0.05	0.84±0.06
	Color	—	natural	
Outer Conductor I	Material	—	Tinned annealed copper wire	silver plated annealed copper wire
	Form	—	braid	
	Strand	mm	0.05	0.08
	Construction	—	6×16	3×16
	Coverage	%	Min. 90	
	Diameter	mm	Nom. 1.05	1.24±0.07
Jacket	Material	—	Fluoroethylene-propylene(FEP)	Ethylene-tetrafluoroethylene(ETFE)
	Thickness	mm	Nom. 0.10	0.12
	Diameter	mm	1.25±0.13	1.48±0.08
	Color	—	Black, White, Red, Green, Yellow, Brown, Blue, Orange, Gray, Violet	
Unit length	m	305	100	
Package	—	paper reel	paper reel	
Approx. mass	kg/km	4.0	5.1	
Inner Conductor resistance at 20°C	Ω/km	Max. 844	Max. 832	
Dielectric strength*	—	A.C. 1000V for 1minute		
Insulation resistance* at 20°C	MΩ·km	Min. 1000		
Characteristic impedance by TDR	Ω	50±2		
Capacitance * at 1kHz	pF/m	Nom. 100	95±10	
Nominal attenuation	at 1GHz	dB/m	1.56	1.8
	at 2GHz	dB/m	2.3	2.5
	at 3GHz	dB/m	2.9	3.1
	at 4GHz	dB/m	3.5	4.1
	at 5GHz	dB/m	4.5	4.6
	at 6GHz	dB/m	5.2	5.3

* Between inner conductor and outer conductor

Table 2 Construction and Properties (32AWG)

Item		Unit	Specified Value		
HCL P/N		—	UL1745-SB CX-50 1×32AWG(7/0.08)D=1.13	UL1745-SB CX-50 1×32AWG(7/0.08)D=1.32	UL1745-DSB CX-50 1×32AWG(7/0.08)D=1.32
HCLI-TPE P/N		—	RFX50-SS32-113	RFX50-SS32-132	RFX50-DS32-132
Inner Conductor	Material	—	silver plated annealed copper wire		
	AWG size	—	32		
	Stranding	No./mm	7/0.08		
	Diameter	mm	0.24		
	Number	—	1		
Insulation	Material	—	Fluoroethylene-propylene(FEP)		
	Thickness	mm	Nom. 0.21		
	Diameter	mm	0.68 ^{+0.04} _{-0.02}		
	Color	—	Natural		
Outer Conductor I	Material	—	Silver plated annealed copper wire	Tinned annealed copper wire	
	Form	—	Braid		
	Strand	mm	0.05		
	Construction	—	4×16		
	Coverage	%	Min. 90		
	Diameter	mm	Nom. 0.88		
Outer Conductor II	Material	—	—	Tinned annealed copper wire	
	Form	—	—	braid	
	Strand	mm	—	0.05	
	Construction	—	—	6×16	
	Coverage	%	—	Min. 90	
	Diameter	mm	—	Nom. 1.12	
Jacket	Material	—	Fluoroethylene-propylene(FEP)		
	Thickness	mm	Nom. 0.125	Nom. 0.22	Nom. 0.10
	Diameter	mm	1.13 ^{+0.08} _{-0.05}	1.32 (Max. 1.45)	1.32±0.1
	Color	—	Black, White, Red, Green, Yellow, Brown, Blue, Orange, Gray, Violet		
Unit length	m	305			200
Package	—	paper reel			Coil
Approx. mass	kg/km	4.0			5.0
Inner Conductor resistance at 20°C	Ω/km	Max. 597			
Dielectric strength*	—	A.C. 500V for 1minute			
Insulation resistance* at 20°C	MΩ·km	Min. 1000			
Characteristic impedance by TDR	Ω	50±2			
Capacitance * at 1kHz	pF/m	Nom. 95			
Nominal attenuation	at 1GHz	dB/m	2.0		
	at 2GHz	dB/m	2.9		
	at 3GHz	dB/m	3.6		
	at 4GHz	dB/m	4.2		
	at 5GHz	dB/m	4.7		
	at 6GHz	dB/m	5.2		

* Between inner conductor and outer conductor

Table 3 Construction and Properties (34AWG, 36AWG)

Item		Unit	Specified Value	
HCL P/N		—	UL1745-SB CX-50 1×34AWG(7/0.064)D=0.98	UL1745-SB CX-50 1×36AWG(7/0.05)D=0.81
HCLI-TPE P/N		—	RFX50-SS34-098	RFX50-SS36-081
Inner Conductor	Material	—	silver plated annealed copper wire	
	AWG size	—	34	36
	Stranding	No./mm	7/0.064	7./0.05
	Diameter	mm	0.192	0.15
	Number	—	1	
Insulation	Material	—	Fluoroethylene-propylene(FEP)	
	Thickness	mm	Nom. 0.169	Nom. 0.125
	Diameter	mm	0.53	0.4 ^{+0.04} _{-0.02}
	Color	—	natural	
Outer Conductor I	Material	—	Tinned annealed copper wire	silver plated annealed copper wire
	Form	—	braid	
	Strand	mm	0.05	
	Construction	—	4×16	3×16
	Coverage	%	Min. 90	
	Diameter	mm	Nom. 0.78	Nom. 0.65
Jacket	Material	—	Fluoroethylene-propylene(FEP)	Perfluoroalkoxy(PFA)
	Thickness	mm	Nom. 0.10	Nom. 0.08
	Diameter	mm	0.98 (Max. 1.1)	0.81 ^{+0.04} _{-0.02}
	Color	—	Black, White, Red, Green, Yellow, Brown, Blue, Orange, Gray, Violet	
Unit length	m	305	305	
Package	—	paper reel	paper reel	
Approx. mass	kg/km	2.4	1.6	
Inner Conductor resistance at 20℃	Ω/km	Max. 868	Max. 1400	
Dielectric strength*	—	A.C. 500V for 1minute	A.C. 1000V for 1minute	
Insulation resistance* at 20℃	MΩ-km	Min. 1500	Min. 1000	
Characteristic impedance by TDR	Ω	50±5	50±3	
Capacitance * at 1kHz	pF/m	Nom. 100	Nom. 100	
Nominal attenuation	at 1GHz	dB/m	2.6	3.1
	at 2GHz	dB/m	3.9	4.7
	at 3GHz	dB/m	5.0	5.8
	at 4GHz	dB/m	6.1	6.9
	at 5GHz	dB/m	7.0	8.2
	at 6GHz	dB/m	7.9	9.4

* Between inner conductor and outer conductor

- **I-PEX Connector**

PRODUCT SPECIFICATION
製品規格

No. PRS-1180

MHF series micro coaxial connector
(at 6GHz)

Qualification Test Report No. TR-1037

2	S2031	K.O	May/17/'02	K.K	Prepared by	Reviewed by	Approved by
1	S1063	K.O	Dec/25/'01	K.K	K.Ohbayashi Nov/16/'01	E.Kawabe Nov/20/'01	K.Katabuchi Nov/21/'01
0	S1055	K.O	Nov/16/'01				
REV.	ECN	BY	DATE	APP.			
REVISION RECORD							

DOCUMENT CLASSIFICATION	TITLE	No.
Product Specification 製品規格	MHF series micro coaxial connector	PRS-1180
<p>1. Scope / 序言 MHF series micro coaxial connector is a wire to board connector for AWG#32 coaxial cable . MHF series micro coaxial connector は、AWG # 32同軸ケーブルの基板対ワイヤーコネクタである。</p> <p>2. Objectives / 目的 This specification covers the requirements for product performance and test methods of MHF series microcoaxial connector 本規格は、MHF series micro coaxial connector の性能と試験条件について規定する。</p> <p>3. Part No. , construction , material and finish / 構成、材料及び仕上げ (1) Part No. Plug : 20278-101R-13, 20278-111R-13 Receptacle : 20279-001E-01 (2) Construction, material and finish of the connector are covered as each drawings. 構成、材料及び仕上げは、各図面に指定されている通りとする。</p> <p>4. Applicable cable / 適合ケーブル 4-1 Part No. 20278-101R-13, 20278-111R-13 (1) Description Inner conductor : AWG#32(7/0.08) Silver plating annealed copper wire or silver plating tin-copper alloy Dielectric core : Fluoro-plastics , diameter 0.68(+0.04,-0.02)mm , nominal thickness 0.22mm Outer conductor : 16/4/0.05 , nominal diameter 0.93mm , silver plating annealed copper wire Jacket : Fluoro-plastics , diameter 1.13(+0.08,-0.05)mm , nominal thickness 0.1mm (2) Requirements Characteristic impedance : 50(+2,-2)ohm by TDR method (raise time 40ps) Nominal capacitance: 97 pF/m Conductor resistance of inner conductor at 293K (20°C) : 520 ohm/km MAX. Insulation resistance : 1500 mega-ohm.km MIN. Dielectric withstand voltage : no breakdown at AC1000V for 1 minutes.</p> <p>(1) 構成 中心導体 : AWG # 32(7/0.08), 銀メッキ軟銅線または銀メッキすず入り銅線 誘電体 : フッ素樹脂, 外径0.68(+0.04,-0.02), 標準厚さ0.22mm 外部導体 : 16/4/0.05, 標準外径0.93mm, 銀メッキ軟銅線 ジャケット : フッ素樹脂, 外径1.13(+0.08,-0.05)mm, 標準厚さ0.1mm</p> <p>(2) 仕様 特性インピーダンス : 50±2Ω (TDR, ライズタイム40ps) 標準静電容量 : 97pF/m 293K(20°C)時の中心導体導体抵抗 : 520Ω /km以下 絶縁抵抗 : 1500MΩ・km以上 耐電圧 : AC1000V・1分間にて絶縁破壊の無い事</p> <p>5. Ratings / 定格 (1) Rated voltage / 電圧 : AC60Vrms (2) Nominal characteristic impedance / 公称特性インピーダンス : 50Ω (3) Frequency / 周波数 : DC~6GHz (4) VSWR : 1.3 MAX. DC~3GHz, 1.5 MAX. 3~6GHz (5) Service Temperature / 使用温度範囲 : 233~363K(-40~+90°C)</p>		

DOCUMENT CLASSIFICATION Product Specification 製品規格	TITLE MHF series micro coaxial connector	No. PRS-1180
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6. Test methods and performance / 試験及び性能

6-1 Test condition / 試験条件

Unless otherwise specified, all tests and measurements shall be performed under the following conditions in accordance with MIL-STD-202

全ての測定と試験は、MIL-STD-202 に基づき以下の条件で行う。

Temperature / 温度 : 288~308K (15~35°C)

Humidity / 湿度 : 45~75%RH

6-2 Sample quantity / 試料数

- (1) Insulation resistance / 絶縁抵抗 : 10pcs.
- (2) Dielectric withstanding voltage / 耐電圧 : 10pcs.
- (3) VSWR : 5pcs.
- (4) Unmating force / 抜去力 : 10pcs
- (5) Durability / 耐久性 : 10pcs.
- (6) Cable retention force / ケーブル保持力 : 10pcs.
- (7) Vibration / 振動 : 10pcs.
- (8) Shock / 衝撃 : 10pcs.
- (9) Thermal shock / 温度サイクル : 10pcs.
- (10) Humidity / 湿度 : 10pcs.
- (11) Salt water spray / 塩水噴霧 : 10pcs.
- (12) Solderability / 半田付け性 : 10pcs.
- (13) Reflow soldering heat resistance / 半田耐熱性 : 10pcs.

6-3-1 Electrical / 電氣的性能

(1) Contact Resistance / 接触抵抗

A. Testing: Solder the receptacle connector to the test board and mate the plug connector together, then measure the contact resistance as shown in Fig.1 by the four terminal method. Apply the low level condition in accordance with MIL-STD-202, Method 307.

Open circuit voltage : 20mV MAX

Circuit current : 10mA MAX. (DC or AC1kHz)

Contact resistance of inner contact : <resistance of A-E> - <resistance of B-E>

Contact resistance of ground contact : <resistance of A-D> - <resistance of B-D>

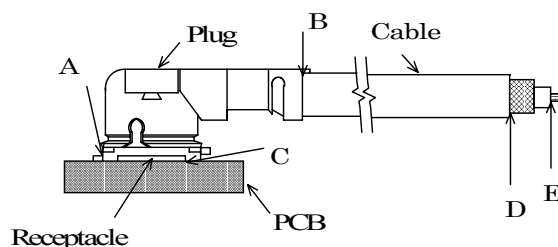


Fig.1

B. Requirements :

Contact resistance of inner contact initial 20 milli-ohm MAX. after testing 25milli-ohm MAX.

Contact resistance of ground contact initial 10 milli-ohm MAX. after testing 15milli-ohm MAX.

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A. 試験法: テスト基板にリセプタクルコネクタを半田付けし、プラグコネクタと嵌合させ、Fig. 1のように4端子法にて下記の条件で測定する。MIL-STD-202 試験法 307 に準拠。

開回路電圧: 20mV以下

試験電流 : 10mA (DCもしくはAC1kHz)

中心導体 : <A-E間の電気抵抗> - <B-E間の電気抵抗>

外部導体 : <A-D間の電気抵抗> - <B-D間の電気抵抗>

B. 必要条件: 中心導体 初期 20mΩ 以下, 試験後 25mΩ 以下

外部導体 初期 10mΩ 以下, 試験後 15mΩ 以下

(2) Insulation resistance / 絶縁抵抗

A. Testing : Mate the plug and receptacle connector together, then apply DC 100 V between the inner contact and the ground contact in accordance with MIL-STD-202, Method 302.

B. Requirements : Initial 500 Mohm MIN. after testing 100 Mohm MIN.

A. 試験法: リセプタクル及びプラグコネクタを互いに嵌合させ、中心導体と外部導体の間に DC 100Vを印加し、測定する。MIL-STD-202 試験法 302 に準拠。

B. 必要条件: 初期 500MΩ 以上 試験後 100MΩ 以上

(3) Dielectric withstanding voltage / 耐電圧

A. Testing : Mate the receptacle and plug connector together, then apply AC 200 Vrms between the inner contact and the ground contact for a minute in accordance with MIL-STD-202, Method 301.

B. Requirements : No creeping discharge, flashover, nor insulator breakdown shall occur.

A. 試験法: リセプタクル及びプラグコネクタを互いに嵌合させ、中心導体と外部導体の間にAC200V(実効値)を一分間印加する。MIL-STD-202 試験法 301 に準拠。

B. 必要条件: 沿面放電、空中放電、絶縁破壊等の異常のないこと。

(4) VSWR

A. Testing : Measure the VSWR as shown in Fig.3 by the network analyzer.

Frequency : 100M~6GHz

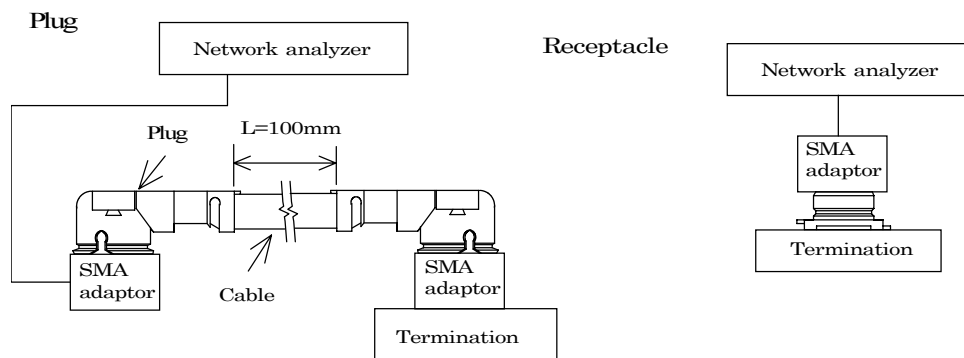


Fig.3

B. Requirements : Plug 1.3 MAX at 0.1~3GHz, . 1.5 MAX at 3~6GHz

Receptacle 1.3 MAX at 0.1~3GHz, . 1.4 MAX at 3~6GHz

A. 試験法: ネットワークアナライザーにて Fig.3 のようにVSWRを測定する。

周波数 : 100M~6GHz

B. 必要条件: Plug 1. 3以下 0. 1~3GHz 1. 5以下 3~6GHz

Receptacle 1. 3以下 0. 1~3GHz 1. 4以下 3~6GHz

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(5) Insertion loss / インサージョンロス

A. Testing : Measure the insertion loss as shown in Fig.5 by the network analyzer.

Frequency : 100M~6GHz

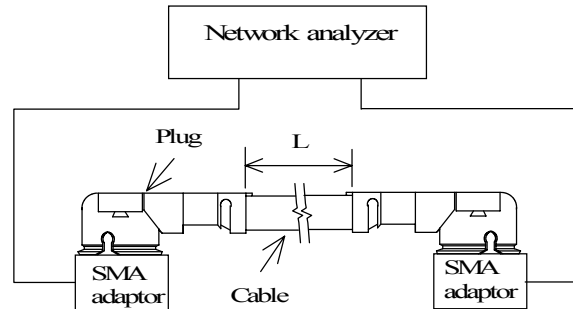


Fig.5

B.Requirements At 0.1~3GHz L=100mm : -1.0dB MIN. L=200mm : -1.4dB MIN.
L=300mm : -1.8dB MIN. L=400mm : -2.1 dB MIN. L=500mm : -2.4 dB MIN.
At 3~6GHz L=100mm : -1.6dB MIN. L=200mm : -2.1dB MIN.
L=300mm : -2.6dB MIN. L=400mm : -3.0 dB MIN. L=500mm : -3.4 dB MIN.

A. 試験法: ネットワークアナライザーにて Fig.5のようにインサージョンロスを測定する。

周波数 : 100M~6GHz

B.必要条件: 周波数100M~3GHz L=100mm : -1.0dB MIN. L=200mm : -1.4dB MIN.

L=300mm : -1.8dB MIN. L=400mm : -2.1 dB MIN. L=500mm : -2.4 dB MIN.

周波数3~6GHz L=100mm : -1.6dB MIN. L=200mm : -2.1dB MIN.

L=300mm : -2.6dB MIN. L=400mm : -3.0 dB MIN. L=500mm : -3.4 dB MIN.

6-3-2 Mechanical / 機械的性能

(1)Unmating force / 挿抜力

A. Testing : Unmate the receptacle connector (soldered to the test board) and plug at a speed
25±3mm/minutes along the mating by the push-on/pull-off machine .

B.Requirements :

Total unmating force : Initial 5N MIN. after 30 cycles 3N MIN.

Unmating force of inner contact : Initial 0.15N MIN. after 30 cycles 0.1N MIN

A. 試験法:挿抜試験機を用いて、基板に半田付けしたリセプタクルとプラグを嵌合軸と平行に毎分25±3mmの速度で挿抜する。

B.必要条件:

初回抜去力: 5N以上 ,30回後抜去力 3N以上

中心導体 :初回抜去力 0.15N以上 ,30回後抜去力 0.1N以上

(2) Durability / 耐久性

A. Testing : Mate and umate the receptacle connector (soldered to the test board) and plug 30 cycles
at a speed 25±3mm/minutes along the mating by the push-on/pull-off machine .

B.Requirements :

Contact resistance of inner contact initial 20 milli-ohm MAX. after testing 25milli-ohm MAX.

Contact resistance of ground contact initial 10 milli-ohm MAX. after testing 15milli-ohm MAX.

A. 試験法:挿抜試験機を用いて、基板に半田付けしたリセプタクルとプラグを嵌合軸と平行に毎分25±3mmの速度で30回挿抜する。

B.必要条件 中心導体接触抵抗 : 初期 20mΩ 以下, 試験後 25mΩ 以下

外部導体接触抵抗 : 初期 10mΩ 以下, 試験後 15mΩ 以下

DOCUMENT CLASSIFICATION Product Specification 製品規格	TITLE MHF series micro coaxial connector	No. PRS-1180
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(3) Cable retention force / ケーブル保持力

A. Testing : Apply force on the cable as shown in Fig.2.

During the testing, run 100mA DC to check electrical discontinuity

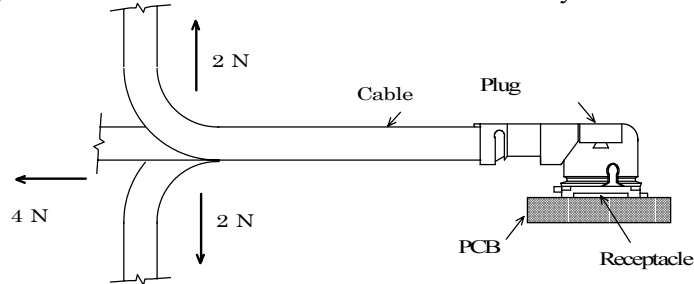


Fig.2

B. Requirements

Appearance : Looseness between the parts, chipping, breakage or other abnormality shall not occur.

Electrical discontinuity : No electrical discontinuity grater than 1 micro-sec. shall occur.

Contact resistance of inner contact initial 20 milli-ohm MAX. after testing 25milli-ohm MAX.

Contact resistance of ground contact initial 10 milli-ohm MAX. after testing 15milli-ohm MAX.

A. 試験法: Fig. 2のようにケーブルに力を加える。尚、試験中にDC100mAの電流を流して電氣的瞬断を確認する。

B. 必要条件 外観 : 部品のゆるみ、欠け、割れ、その他外観上の異常の無いこと。
電流瞬断 : 試験中、1 マイクロ秒を超える電氣的瞬断の無いこと。
中心導体接触抵抗 : 初期 20mΩ 以下、試験後 25mΩ 以下
外部導体接触抵抗 : 初期 10mΩ 以下、試験後 15mΩ 以下

(4) Vibration / 振動

A. Testing : Apply the following vibration to the mating connector .

During the testing, run 100mA DC to check electrical discontinuity.

Frequency : 10Hz → 100Hz → 10Hz / approx 15 minutes.

Half amplitude ,Peak value of acceleration: 1.5mm or 59m/s² (6G)

Directions , cycle : 3 mutually perpendicular direction ,
5 cycles(approx 75min)about each direction

B. Requirements

Appearance : Looseness between the parts, chipping, breakage or other abnormality shall not occur.

Electrical discontinuity : No electrical discontinuity grater than 1micro-sec. shall occur.

Contact resistance of inner contact initial 20 milli-ohm MAX. after testing 25milli-ohm MAX.

Contact resistance of ground contact initial 10 milli-ohm MAX. after testing 15milli-ohm MAX.

A. 試験法: 嵌合状態のコネクタを、下記の振動を加える。尚、試験中にDC100mAの電流を流して電氣的瞬断を確認する。

周波数 : 10Hz→100Hz→10Hz / 約15分間

片振幅,加速度: 1.5mm or 59m/s² (6G)

方向,サイクル: 3 つの互いに直角な方向について各5サイクル(約75分)実施

B. 必要条件 外観 : 部品のゆるみ、欠け、割れ、その他外観上の異常の無いこと。
電流瞬断 : 試験中、1 マイクロ秒を超える電氣的瞬断の無いこと。
中心導体接触抵抗 : 初期 20mΩ 以下、試験後 25mΩ 以下
外部導体接触抵抗 : 初期 10mΩ 以下、試験後 15mΩ 以下

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(5) Shock / 衝撃

A. Testing : Apply the following vibration to the mating connector in accordance with MIL-STD-202, Method 213, Condition B. During the testing, run 100mA DC to check electrical discontinuity.

Peak value of acceleration: 735m/s^2 (75G)

Duration : 11msec

Wave Form : half sinusoidal

Directions , cycle : 6 mutually perpendicular direction , 3 cycles about each direction

B.Requirements

Appearance : Looseness between the parts, chipping, breakage or other abnormality shall not occur.

Electrical discontinuity : No electrical discontinuity grater than 1 micro-sec. shall occur.

Contact resistance of inner contact initial 20 milli-ohm MAX. after testing 25milli-ohm MAX.

Contact resistance of ground contact initial 10 milli-ohm MAX. after testing 15milli-ohm MAX.

A. 試験法: 嵌合状態のコネクタを、衝撃試験機に取り付け、下記の衝撃を加える。尚、試験中にDC100mAの電流を流して電氣的瞬断を確認する。MIN-STD-202 試験法 213 試験条件 B に準拠。

最大加速度: 735m/s^2 (75G)

標準持続時間: 11msec.

波形: 半波正弦波

方向: 直交する6方向、各3回

B. 必要条件 外観 : 部品のゆるみ、欠け、割れ、その他外観上の異常の無いこと。

電流瞬断 : 試験中、1 マイクロ秒を超える電氣的瞬断の無いこと。

中心導体接触抵抗 : 初期 20mΩ 以下、試験後 25mΩ 以下

外部導体接触抵抗 : 初期 10mΩ 以下、試験後 15mΩ 以下

6-3-3 Environmental / 耐環境性

(1) Thermal shock/ 温度サイクル

A. Testing : Apply the following environment to the mating connector .

Temperature ,duration

:233K/30minutes→278~308K/5minutes MAX.→363K/30minutes→278~308K/5minutes MAX.

(-40°C) (5~35°C)

(90°C)

(5~35°C)

No. of cycles : 5 cycles

B.Requirements

Appearance : Looseness between the parts, chipping, breakage or other abnormality shall not occur.

Contact resistance of inner contact initial 20 milli-ohm MAX. after testing 25milli-ohm MAX.

Contact resistance of ground contact initial 10 milli-ohm MAX. after testing 15milli-ohm MAX.

Insulation resistance : initial 500 mega-ohm MIN. after testing 100 mega-ohm MIN.

A. 試験法: 嵌合状態のコネクタを、下記の雰囲気放置する。

1サイクルの条件

:233K/30分→278~308K/5分以下→363K/30分→278~308K/5分以下

(-40°C) (5~35°C)

(90°C)

(5~35°C)

実施サイクル :5サイクル

B. 必要条件 外観 : 部品のゆるみ、欠け、割れ、その他外観上の異常の無いこと。

中心導体接触抵抗 : 初期 20mΩ 以下、試験後 25mΩ 以下

外部導体接触抵抗 : 初期 10mΩ 以下、試験後 15mΩ 以下

絶縁抵抗 : 初期 500MΩ 以上 試験後 100MΩ 以上

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(2) Humidity / 湿度

A. Testing : Apply the following environment to the mating connector in accordance with MIL-STD-202, Method 103, Condition B .

Temperature : 313 ± 2 K (40 ± 2 °C)

Humidity : 90~95%RH

Duration : 96 hours

B.Requirements

Appearance : Looseness between the parts, chipping, breakage or other abnormality shall not occur.

Contact resistance of inner contact initial 20 milli-ohm MAX. after testing 25milli-ohm MAX.

Contact resistance of ground contact initial 10 milli-ohm MAX. after testing 15milli-ohm MAX.

Insulation resistance : initial 500 mega-ohm MIN. after testing 100 mega-ohm MIN.

A. 試験法: 嵌合状態のコネクタを、下記の雰囲気中に放置する。MIL-STD-202 試験法 103 条件 B に準拠。

温度: 313 ± 2 K (40 ± 2 °C)

湿度: 90~95%RH

時間: 96時間

B. 必要条件 外観 : 部品のゆるみ、欠け、割れ、その他外観上の異常の無いこと。

中心導体接触抵抗 : 初期 20mΩ 以下、試験後 25mΩ 以下

外部導体接触抵抗 : 初期 10mΩ 以下、試験後 15mΩ 以下

絶縁抵抗 : 初期 500MΩ 以上 試験後 100MΩ 以上

(3) Salt water spray / 塩水噴霧

A. Testing : Apply the following environment to the mating connector in accordance with MIL-STD-202, Method 101, Condition B.

Temperature : 308 ± 2 K (35 ± 2 °C)

Salt water density by weight : 5 ± 1 %

Duration : 48 hours

B.Requirements : Appearance no abnormality adversely affecting the performance shall occur.

A. 試験法: 嵌合状態のコネクタを、下記の雰囲気中に放置する。

温度 : 308 ± 2 K (35 ± 2 °C)

塩水濃度: 5 ± 1 % (重量比)

時間 : 48時間

B. 必要条件 : 外観 著しい腐食の無い事。

6-3-4 Solder / 半田付け関連

(1) Solderability / 半田付け性

A. Testing : Dip the solder tine of the contact in the solder bath at 518 ± 5 (245 ± 5 °C) for 5 ± 0.5 sec.

After immersing the tine in the flux of RMA or R type for 5 to 10 seconds in accordance with MIL-STD-202, Method 208.

B.Requirements : More than 95% of the dipped surface shall be evenly wet.

A. 試験法: コントクトの半田付け部を 518 ± 5 K (245 ± 5 °C)の半田槽内に 5 ± 0.5 秒浸す。フラックスは、RMA 又は R 型を使用し 5~10 秒間浸すものとする。MIL-STD-202, 試験法 208 に準拠。

B. 必要条件: 浸した面積の 95%以上に半田がむらなく付着すること。

(2) Reflow soldering heat resistance / 半田耐熱性

A. Testing : Put on the receptacle connector to PCB , apply the heat 2 cycles as shown in Fig. 4

B.Requirements : Appearance no abnormality adversely affecting the performance shall occur.

A. 試験法: 基板にリセプタクルコネクタを置き、Fig. 4の条件で2回リフローを行う。

B. 必要条件: 機能を損なう変形及び欠陥の無い事。

<p>DOCUMENT CLASSIFICATION</p> <p>Product Specification 製品規格</p>	<p>TITLE</p> <p>MHF series micro coaxial connector</p>	<p>No.</p> <p>PRS-1180</p>
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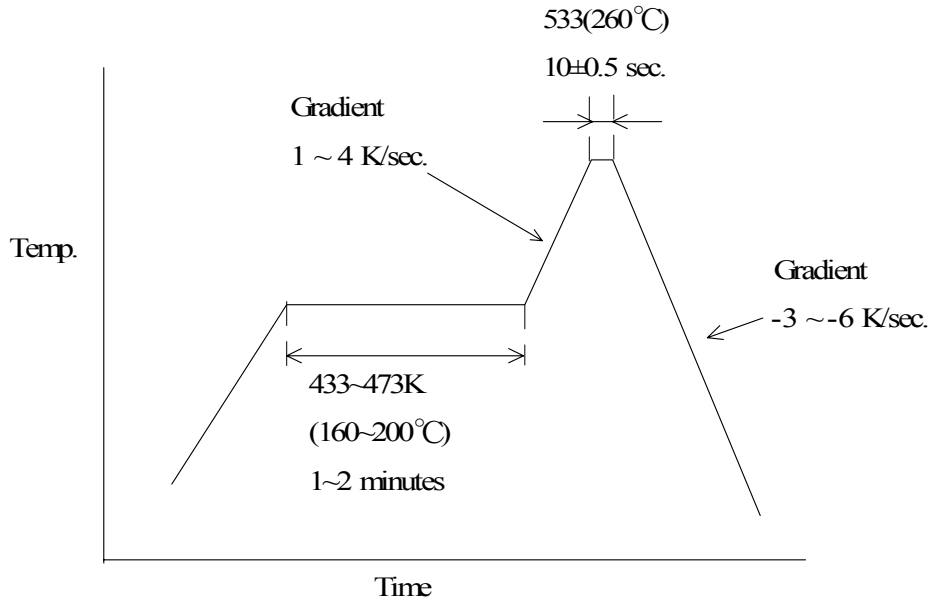


Fig4

● PCB



NAN YA PLASTICS CORPORATION
 ELECTRONIC MATERIALS DIVISION
COPPER CLAD LAMINATE DEPARTMENT

**Glass cloth base epoxy resin
 flame retardant copper clad laminate**

NO. 201, TUNG HWA N. ROAD,
 TAIPEI, TAIWAN, ROC

FEATURES

- High T_g: 175°C (DSC)
- Excellent dimensional stability through-hole reliability
- Excellent electrical, chemical and heat resistance properties
- IPC-4101A specification is applicable
- U.L. designation: ANSI grade FR-5
- U.L. file number E98983(s)
- Outstanding heat resistance
- High luminance of multi-functional epoxy contrast with copper for A.O.I.
- Traditional FR-4 methods processability

PERFORMANCE LIST

Characteristics	Unit	Conditioning	Typical Values	SPEC	
Volume resistivity	MΩ-cm	C-96/35/90	5.0 x 10 ⁹	10 ⁷ ↑	
Surface resistivity	MΩ	C-96/35/90	4.1 x 10 ⁹	10 ⁸ ↑	
Permittivity 1MHZ	-	C-24/23/50	4.2-4.8	5.4 ↓	
Loss Tangent 1MHZ	-	C-24/23/50	0.010-0.016	0.035 ↓	
Arc resistance	SEC	D-48/50+D-0.5/23	120 ↑	90 ↑	
Dielectric breakdown	KV	D-48/50	60 ↑	40 ↑	
Moisture absorption	%	D-24/23	< 0.78mm	0.18	0.80 ↓
			≥ 0.78mm	0.15	0.35 ↓
Flammability	-	C-24/23/50+E-24/125	94V0	94V0	
Peel strength 1oz	lb/in	288°C x 10" solder floating	10	8 ↑	
Heat resistance	SEC	288°C dipping	600 ↑	10 ↑	
Glass transition temp	°C	DSC	175 ± 5	N/A	
Dimensional stability X-Y axis	%	E 4/105	0.01-0.03	0.05 ↓	
Coefficient of thermal expansion					
Z-axis before T _g	In/in/°C	TMA	5.0 x 10 ⁻⁵	N/A	
Z-axis after T _g	In/in/°C	TMA	25.0 x 10 ⁻⁵		

Data shown are nominal values for reference only.

■ **CONSTRUCTION:**

THICKNESS		CONSTRUCTION		THICKNESS		CONSTRUCTION	
mm	Mil			mm	mil		
0.10	4	1080	2 plies	0.38	15	7628	2 plies
0.11	4	2116	1 ply	0.45	18	7628x2+1080x1	
0.13	5	1080	2 plies	0.50	20	7628	3 plies
0.13sp	5	2116	1 ply	✓0.53	21	7628	3 plies
0.15	6	1506	1 ply	✓0.60	24	7628	3 plies
0.16	6	2112	2 plies	0.77	31	7628	4 plies
0.21	8	7628	1 ply	0.8	32	7628	4 plies
0.26	10	2116	2 plies	0.9	36	7628	5 plies
0.30	12	2116	3 plies	1.0	39	7628	5 plies
0.30sp	12	1506	2 plies	1.1	43	7628	6 plies
0.35	14	7628	2 plies	1.2	47	7628	6 plies

*1.2,1.1,1.0,0.9,0.77mm, THICKNESS INCLUDES CLADDING. ALL OTHERS EXCLUDE CLADDING.

■ **PRODUCT SIZE & THICKNESS**

THICKNESS INCH (mm)	COPPER CLADDING OZ (μm)	SIZE		THICKNESS TOLERANCE
		INCH	mm	
0.004(0.1)	0.5(17)	48.8 x 36.6	1240 x 0930	IPC-4101A SPEC CLASS C/M
to	1.0(35)	48.8 x 40.5	1240 x 1030	
0.039(1.0)	2.0(70)	48.8 x 42.5	1240 x 1080	

■ Keeping the core and prepreg in the same grain direction is crucial to ensure the flatness of multilayer boards.

Grain direction is shown on the Certificate of Conformance.

■ This material can not be used in horizontal brown oxide process.

■ **CERTIFICATION UL : E98983 (S)**

Minimum Material Thickness Inch (mm)	Clad cond. Thickness min. max. mils mils (mic) (mic)	Max. Area Diameter Inch (mm)	Sold Lts Temp Time °C sec	UL 94 Flame class	Max. Operating Temp
0.004 (0.101)	0.68 4.08 (17) (102)	2.0 (50.8)	300 30	94V-0	140

Dk-Df Table

Frequency	Dk	Min Dk	Max Dk	Df	Min Df	Max Df
1 MHz	3.92	3.82	4.02	0.0089	0.0087	0.0091
500 MHz	3.92	3.82	4.02	0.0090	0.0088	0.0092
1 GHz	3.92	3.82	4.02	0.0091	0.0090	0.0093
1.5 GHz	3.92	3.82	4.02	0.0092	0.0091	0.0094
2 GHz	3.92	3.82	4.02	0.0094	0.0092	0.0095
2.5 GHz	3.92	3.82	4.02	0.0095	0.0093	0.0097
3 GHz	3.92	3.82	4.02	0.0096	0.0094	0.0098
3.5 GHz	3.92	3.82	4.02	0.0097	0.0096	0.0099
4 GHz	3.92	3.82	4.02	0.0099	0.0097	0.0100
4.5 GHz	3.92	3.82	4.02	0.0100	0.0098	0.0101
5 GHz	3.92	3.82	4.02	0.0101	0.0099	0.0103
5.5 GHz	3.92	3.82	4.02	0.0102	0.0100	0.0104
6 GHz	3.92	3.82	4.01	0.0103	0.0102	0.0105
6.5 GHz	3.92	3.82	4.01	0.0105	0.0103	0.0106
7 GHz	3.92	3.82	4.01	0.0106	0.0104	0.0107
7.5 GHz	3.92	3.82	4.01	0.0107	0.0105	0.0109
8 GHz	3.92	3.82	4.01	0.0108	0.0106	0.0110
8.5 GHz	3.92	3.82	4.01	0.0109	0.0108	0.0111
9 GHz	3.92	3.82	4.01	0.0111	0.0109	0.0112
9.5 GHz	3.91	3.82	4.01	0.0112	0.0110	0.0114
10 GHz	3.91	3.82	4.01	0.0113	0.0111	0.0115
10.5 GHz	3.91	3.82	4.01	0.0114	0.0112	0.0116
11 GHz	3.91	3.82	4.01	0.0115	0.0114	0.0117
11.5 GHz	3.91	3.82	4.01	0.0117	0.0115	0.0118
12 GHz	3.91	3.82	4.01	0.0118	0.0116	0.0120

- **Sony T4000**

TECHNICAL REPORT

Industrial Adhesive Tape T4000

Industrial Adhesive Tape T4000

Double-Faced Adhesive Tape

T4000 is a double-faced adhesive tape developed for the requirement of strong and permanent bonding. It is a highly selected double-faced adhesive tape with outstanding reliability, having high low-temperature adhesion.

SPECIFICATIONS

Coating amounts (N/m ²)	1.40~1.70
Coating thickness (mm)	approx. 0.15
Thickness of release paper (mm)	approx. 0.14

FEATURES

- Excellent in thermal holding strength
- Excellent in low-temperature adhesion
- High bonding strength in the widest temperature range
- No smell
- Outstanding reliability and durability

APPLICATION

T4000 is most suitable for the adhesion to surface decorative sheet, rating plate and escutcheon, etc. made of metal and plastic material for the automobiles and household electric appliances.

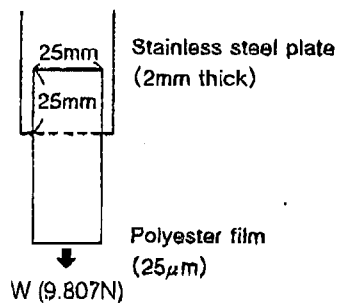
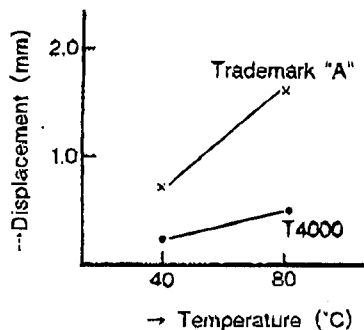
T4000 is also recommendable for use as a double-faced permanent adhesive tape for various substrates.

Industrial Adhesive Tape T4000

SPECIFICATIONS

1. Holding strength at elevated temperatures

T4000 demonstrates an excellent holding strength even under severe conditions.



Conditions for preparing test pieces

Temperature : 20°C

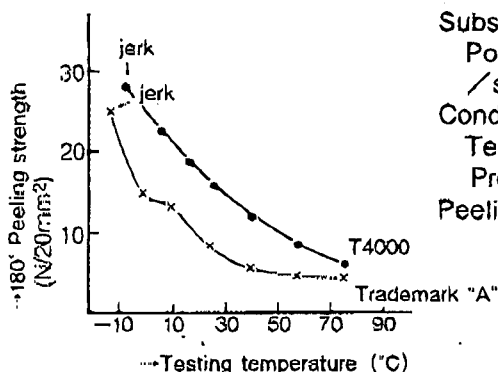
Pressure : 20N/cm² (one stroke)

Conditions for test peeling

60minutes ; 9.80N of loading

2. Temperature change of 180° peeling strength

T4000 provides a high bonding strength at various temperatures



Substrate :

Polyester film (25µm)

/ stainless steel plate (2mm thick)

Conditions for preparing test pieces

Temperature : 20°C

Pressure : 20N/cm² (one stroke)

Peeling speed : 300mm/min.

3. Peeling strength after aging

T4000 has excellent thermal aging resistance, and high resistances to moisture, water, oil and weather.

Substrate : Polyester film (25µm)/stainless steel plate (2mm thick)

Conditions for preparing test pieces :

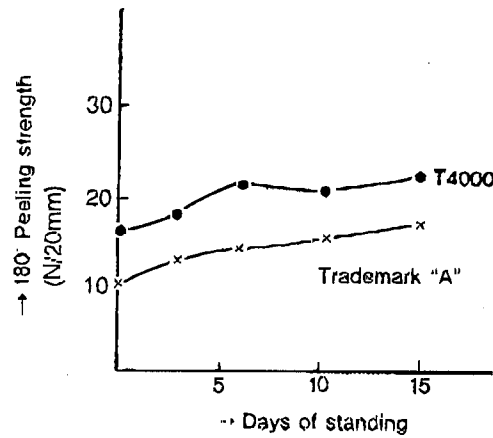
Temperature : 20°C

Pressure : 20N/cm² (one stroke)

Test peeling speed : 300m/min.

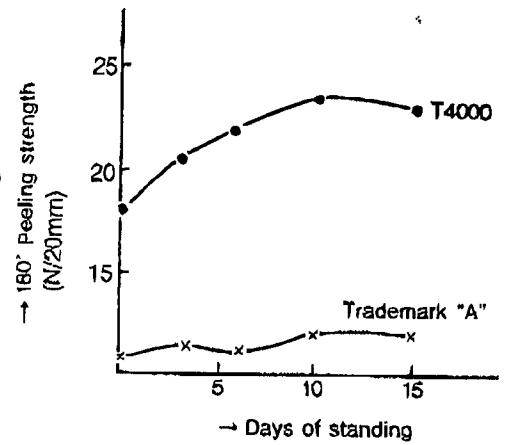
● THERMAL AGING

Standing test in the atmosphere



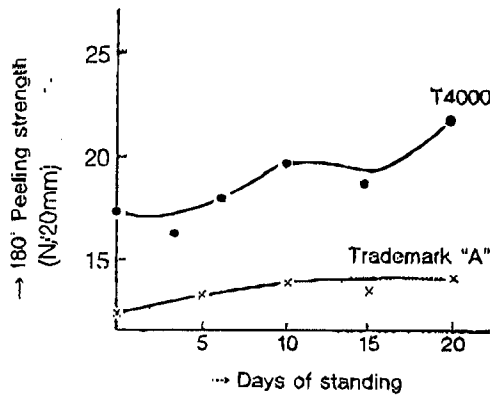
● MOISTURE RESISTANCE

Standing test in the atmosphere of 50°C and relative humidity of 90 %



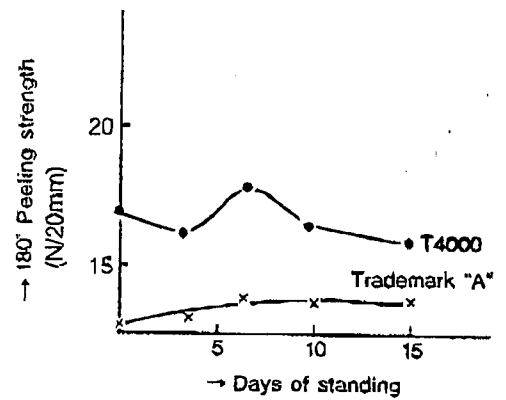
● WATER RESISTANCE

standing test in water at 40°C

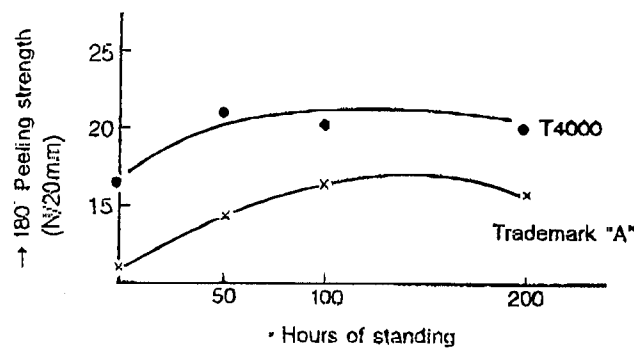


● OIL RESISTANCE

Standing test in machine oil at 40°C



● WEATHERING

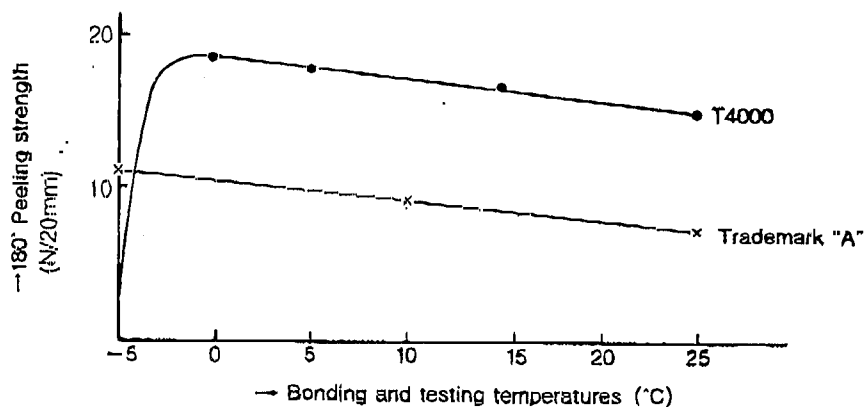


Industrial Adhesive Tape T4000

WORKABILITY

Low-temperature adhesion

T4000 provides high adhesion even in the bonding work at low temperatures.



CAUTION: While this report is based on our company's reliable testing, this does not imply that the effects noted herein are guaranteed. The user is requested to use this product at his own risk after thorough study of the purposes for which the product is designed and the conditions under which it is used.

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Printed 2001.7

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ONY CHEMICALS CORP

ANUMA FACTORY

8 SATSUKI-CHO

ANUMA-SHI

OCHIGI-KEN 322-8501, JAPAN

MH15431

resure sensitive laminating adhesives: NP203, NP203W. For bonding aluminum (thickness:007 to 0.020 in), polycarbonate (thickness:019 to 0.079 in) and acrylic (thickness:019 to 0.079 in) to acrylonitrile butadiene (ABS) plastic, maximum surface temperature 80 C (176 F), minimum temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

3303, NP303W. For bonding aluminum (thickness:007 to 0.020 in), polycarbonate (thickness:019 to 0.079 in) and acrylic (thickness:019 to 0.079 in) to acrylonitrile butadiene styrene (ABS) plastic, maximum surface temperature 80 C (176 F), minimum temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

3500, T3500S, T3500SW, T3500W. For bonding aluminum (thickness:007 to 0.020 in), polycarbonate (thickness:019 to 0.079 in) and acrylic (thickness:019 to 0.079 in) to acrylonitrile butadiene styrene (ABS) plastic, maximum surface temperature 80 C (176 F), minimum temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

4000, T4000W. For bonding aluminum (thickness:007 to 0.020 in), polycarbonate (thickness:019 to 0.079 in) and acrylic (thickness:019 to 0.079 in) to acrylonitrile butadiene styrene (ABS) plastic, maximum surface temperature 80 C (176 F), minimum temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1000B, T4000BW. For bonding aluminum (thickness:007 to 0.020 in), polycarbonate (thickness:019 to 0.079 in) and acrylic (thickness:019 to 0.079 in) to acrylonitrile butadiene styrene (ABS) plastic, maximum surface temperature 80 C (176 F), minimum temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1500B, T4500BW. For bonding aluminum (thickness:007 to 0.020 in), polycarbonate (thickness:019 to 0.079 in) and acrylic (thickness:019 to 0.079 in) to acrylonitrile butadiene styrene (ABS) plastic, maximum surface temperature 80 C (176 F), minimum temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1700M. For bonding aluminum (thickness:002 to 0.032 in) and acrylic (thickness:019 to 0.079 in) to acrylonitrile butadiene styrene (ABS) plastic, maximum surface temperature 80 C (176 F), minimum temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1000. For bonding aluminum (thickness:002 to 0.032 in) to aluminum, and galvanized steel, max temperature 150 C (302 F) min temperature -40 C (-40 F). Acrylonitrile Butadiene Styrene (ABS) plastic, maximum surface temperature 80 C (176 F), minimum temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1000. For bonding aluminum (thickness:002 to 0.032 in) to aluminum, stainless steel, galvanized steel, alkyl enamel and porcelain, maximum temperature 150 C (302 F) min temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1000. For bonding aluminum (thickness:002 to 0.032 in) to aluminum, stainless steel, galvanized steel, alkyl enamel and porcelain, maximum temperature 150 C (302 F) min temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1000. For bonding aluminum (thickness:002 to 0.032 in) to aluminum, stainless steel, galvanized steel, alkyl enamel and porcelain, maximum temperature 150 C (302 F) min temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1000. For bonding aluminum (thickness:002 to 0.032 in) to aluminum, stainless steel, galvanized steel, alkyl enamel and porcelain, maximum temperature 150 C (302 F) min temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.

1000. For bonding aluminum (thickness:002 to 0.032 in) to aluminum, stainless steel, galvanized steel, alkyl enamel and porcelain, maximum temperature 150 C (302 F) min temperature -40 C (-40 F). Suitable where exposed indoors to high humidity and occasional exposure to water.